



Product Change Notification: MFOL-07KHZH309

Date:

09-Feb-2026

Product Category:

System On Chip Fpgas

Notification Subject:

CCB 7759 Initial Notice: Qualification of ASEM as a new assembly site for A2F500M3G-1PQG208IX3, A2F200M3F-PQG208I, A2F500M3G-PQG208I, A2F500M3G-1PQG208I, A2F500M3G-1PQG208, A2F200M3F-1PQG208I, A2F200M3F-1PQG208, A2F500M3G-PQG208, and A2F200M3F-PQG208 catalog part numbers (CPN) available in 208L MQFP (28X28X3.4mm) package.

Affected CPNs:

[MFOL-07KHZH309_Affected_CPN_02092026.pdf](#)

[MFOL-07KHZH309_Affected_CPN_02092026.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of ASEM as a new assembly site for A2F500M3G-1PQG208IX3, A2F200M3F-PQG208I, A2F500M3G-PQG208I, A2F500M3G-1PQG208I, A2F500M3G-1PQG208, A2F200M3F-1PQG208I, A2F200M3F-1PQG208, A2F500M3G-PQG208, and A2F200M3F-PQG208 catalog part numbers (CPN) available in 208L MQFP (28X28X3.4mm) package.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)

Assembly Site	Amkor Technology Philippine (P1/P2), INC. (ANAP)	ASE Group - Malaysia (ASEM)	Yes
Wire Material	Au	Au	No
Die Attach Material	3230	8143	Yes
Molding Compound Material	G700M	G631SM	Yes
Lead-Frame Material	C194	C7025	Yes
Lead-Frame Paddle Size	234X344 mils	372X372 mils	Yes
Lead-Frame Design	See Pre and Post change summary for comparison.		

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying ASEM as a new assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: June 2026

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	August 2025					>	June 2026				
Work Week	32	33	34	35	36		23	24	25	26	27
Initial PCN Issue Date		X									
Qual Report Availability									X		

Final PCN Issue Date										X		
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Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: August 14, 2025: Issued initial notification.
 February 09, 2026: Re-issued initial notification. Added the "Change (Yes/No) column to the Pre- and Post- Change Summary table. Updated the mold compound material from "G700LY" to "G631SM" in Pre- and Post- Change table and the Qualification Plan. Revised the estimated qualification completion date from March 2026 to June 2026.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

- [PCN_MFOL-07KHZH309_Qualification Plan.pdf](#)
- [PCN_MFOL-07KHZH309_Pre and Post Change Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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